



BOISE STATE UNIVERSITY

Additive Manufacturing for the Rapid Prototyping of Economical Biosensors

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Overview

- As the demand of biological sensors continues to increase, it is important to develop a material that mitigates the ecological footprint, while enhancing the device performance; a promising candidate of which is MXenes with tunable surface functional group, band gap, and mechanical properties.
- Additive electronics manufacturing is a promising technique for the scalable fabrication of various sensors such as optical, gas, force, humidity, and electrochemical sensors. [1]

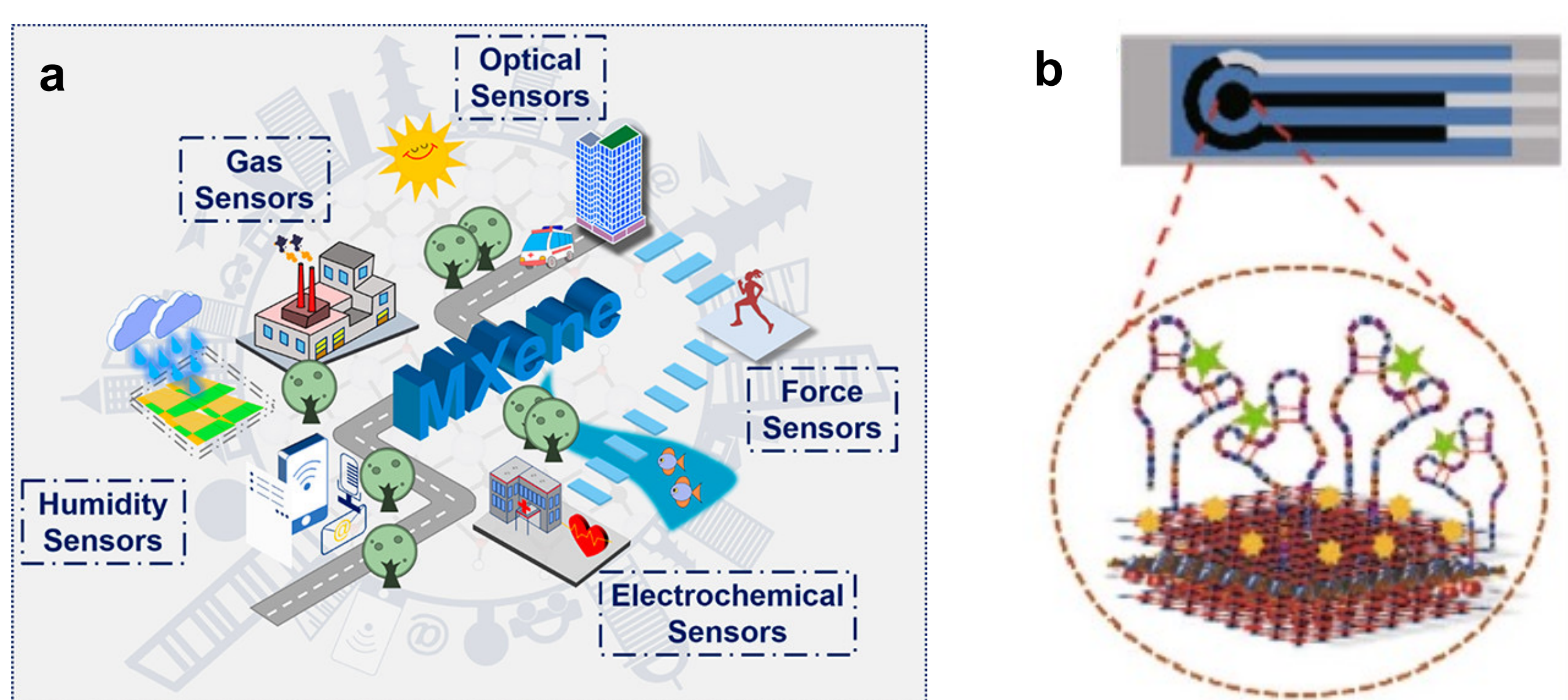


Fig. 1 (a) Schematic diagram of MXene sensors [1]. (b) MXene biosensor for detection through electrochemical method [2].

MXene Synthesis

- Precursors:** Ti_3AlC_2 MAX phases
- Etching:** Required to break strong metallic or covalent bonds, unlike in VdW solids. The aluminum layers are etched using the in situ production of HF through the MILD etching method.
- Delamination:** Produces colloidal solutions of single- or few-layer MXene flakes in water or polar organic solvents.

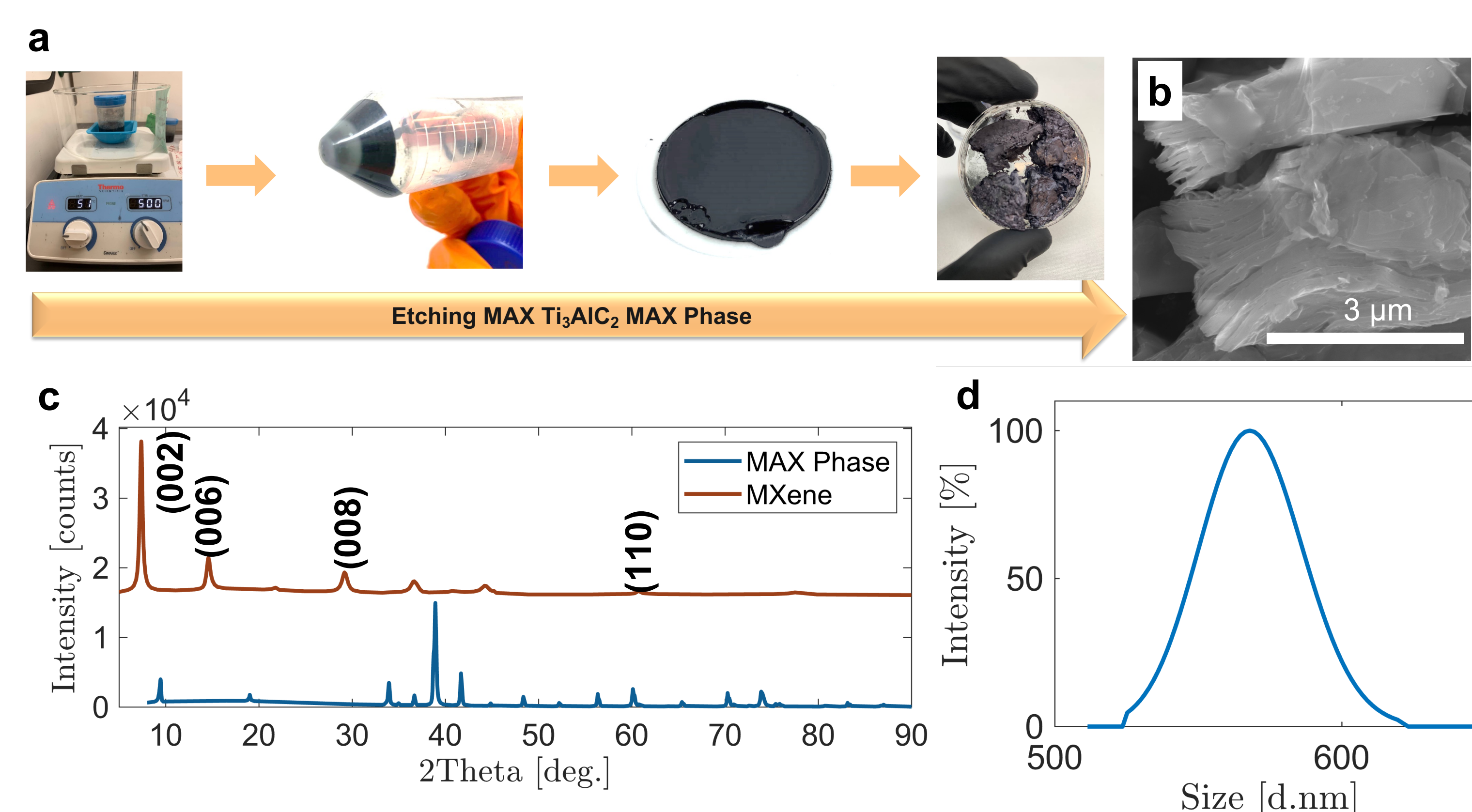


Fig. 2 (a) Photograph of synthesis of multi-layer $Ti_3C_2T_x$ MXene from Ti_3AlC_2 (MAX phase). (b) Scanning electron microscopy (SEM) image of multilayered $Ti_3C_2T_x$ after etching reaction. (c) X-ray diffraction pattern (XRD) of multi-layer $Ti_3C_2T_x$ and Ti_3AlC_2 (MAX phase). There is no peak around 40 degree for Ti_3C_2 , indicating the removal of aluminum layer from MAX phase. (d) Dynamic light scattering (DLS) of exfoliated m-layer $Ti_3C_2T_x$. The size of particles is less than 1 μm which is compatible with aerosol jet printing technology.

Characterization and Ink Formulation

- Size reduction and exfoliation of multi-layered $Ti_3C_2T_x$ to few/mono layer $Ti_3C_2T_x$ is performed by probe-sonicator.
- The resultant NPs are formulated to an ink compatible with AJP technique.
- The rheology parameters such as viscosity, surface tension, contact angle, and density need to be studied before printing.

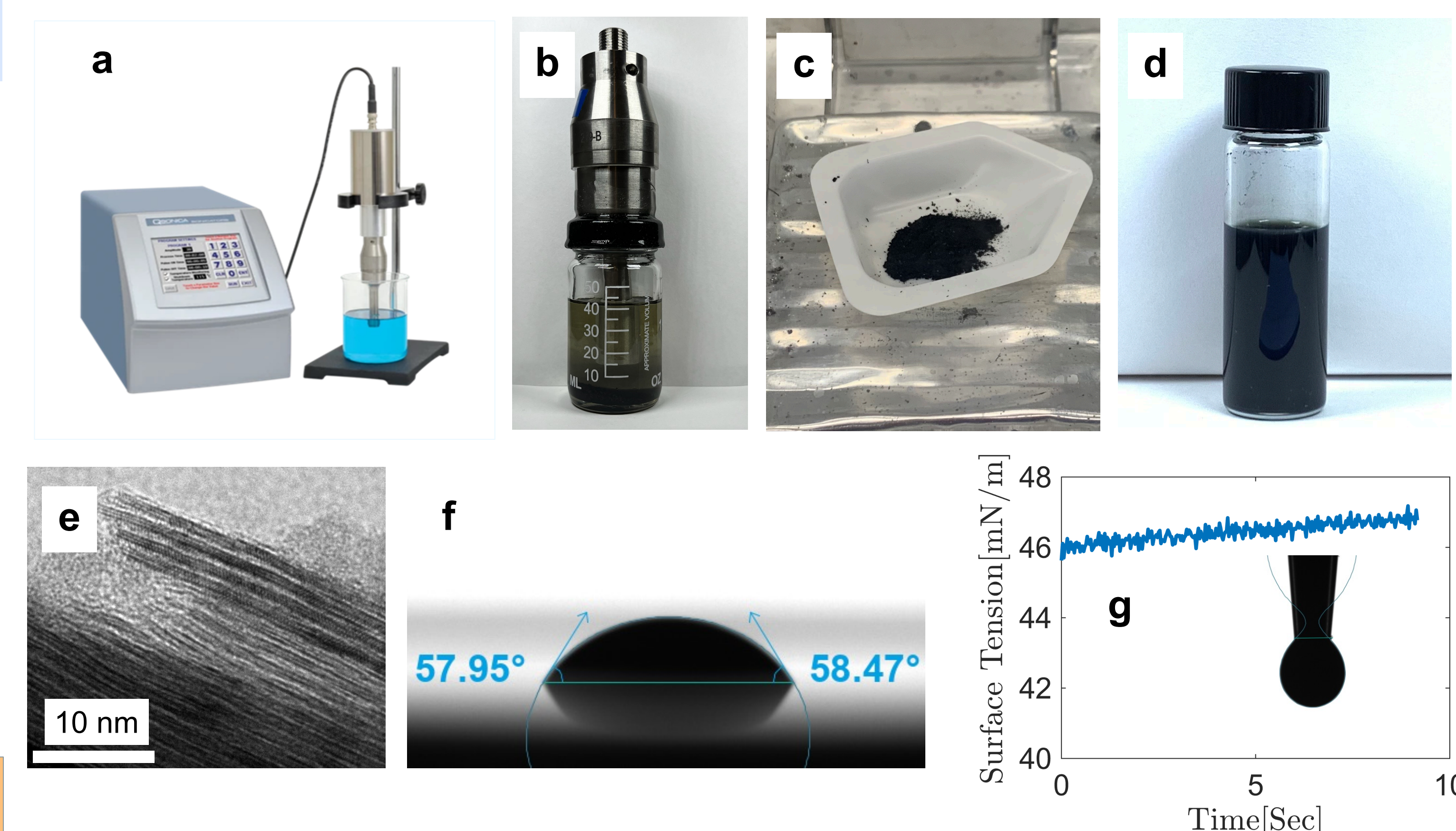


Fig. 3 (a) 700Q Sonica probe sonicator used for exfoliation and size reduction of multi-layer $Ti_3C_2T_x$ MXene. (b) Dispersion of multi-layer $Ti_3C_2T_x$ MXene in organic-based solvent in prepared exfoliation setup to avoid oxidation. (c) Exfoliated $Ti_3C_2T_x$ MXene after washing step and drying step. (d) Formulated ink for AJP technique. (e) TEM image of exfoliated $Ti_3C_2T_x$ MXene (f) Contact angle measurement of formulated ink on Kapton. (g) Surface tension of the formulated ink.

Aerosol Jet Printing of Ti_3C_2

- Aerosol Jet Printing (AJP) is a promising technique for additive electronics manufacturing and is influenced by various variables, including carrier gas flow rate, sheath gas flow rate, nozzle diameter, and atomization frequency.
- This work will enable the manufacturing of biosensors based on Ti_3C_2 MXene inks using high-resolution AJP techniques, with specific focus on cortisol based sensors.

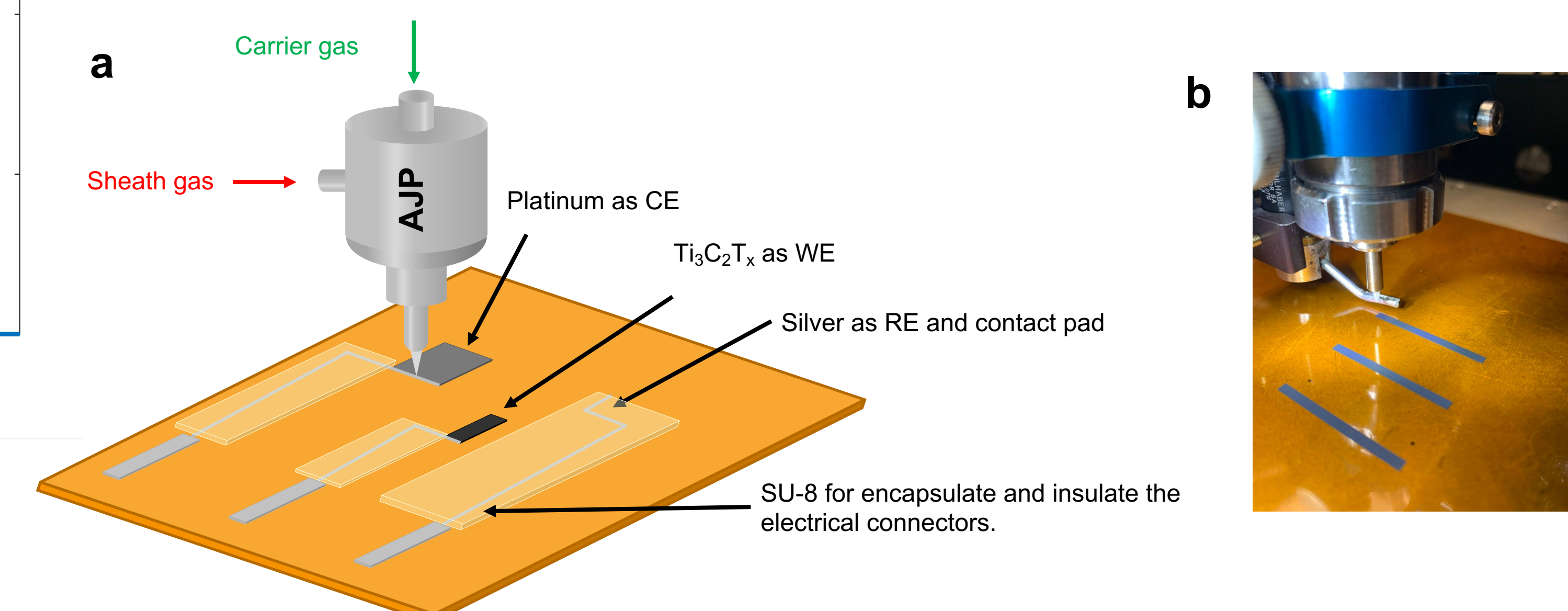


Fig. 4 (a) Schematic illustration of electrochemical sensors using $Ti_3C_2T_x$ MXene, platinum, silver, and SU-8 inks on Kapton for biosensors. (b) Printing of $Ti_3C_2T_x$ lines on Kapton showing the printability of the formulated $Ti_3C_2T_x$ MXene

Post-printing Process and Device Geometry

- Post-printing process technique is employed after printing step to achieve bulk-like performance.
- Here we used annealing the printing structure at 300 °C under Ar/ N_2 gas to remove the solvents from the printed structure.
- The inert condition needs to be performed to avoid oxidation for printed structure.

The electrochemical sensor will have three electrode design with:

- Printed platinum ink as counter electrode.
- Printed $Ti_3C_2T_x$ ink as working electrode.
- Printed silver ink as reference electrode.
- The SU-8 will be used to encapsulate and insulate the electrical connectors.

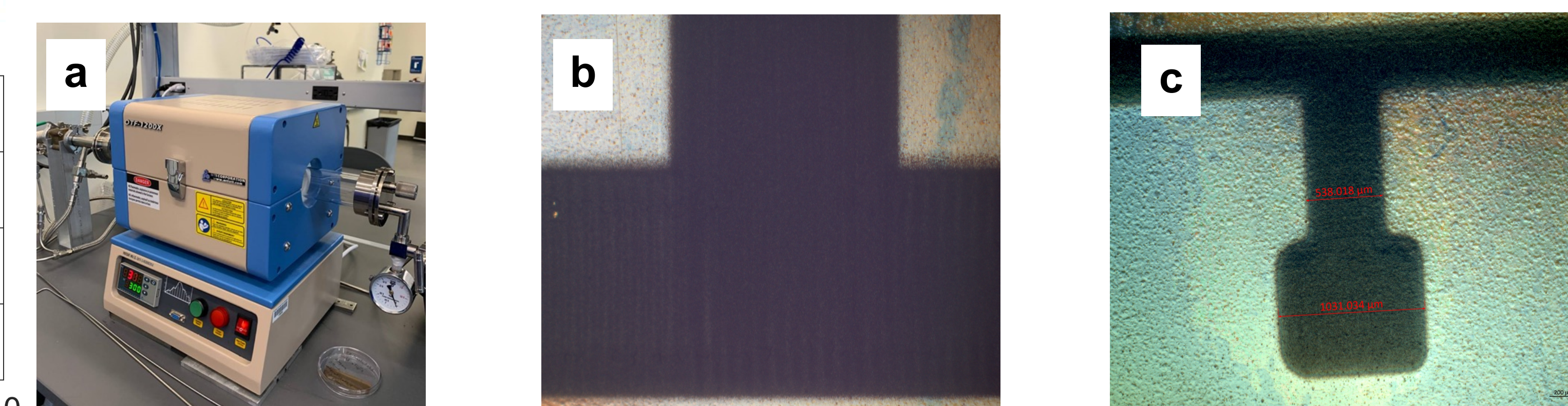


Fig. 5 (a) Tube furnace for post-printing process for printed devices. (b, c) optical image of some printed $Ti_3C_2T_x$ MXene ink on Kapton after post-printing process showing the formulated ink and printing parameters optimized properly.

Conclusion/ Future Work

The next steps will be:

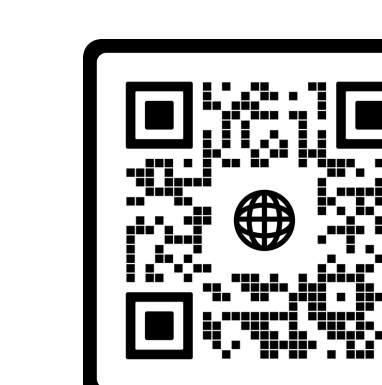
- Rheology and contact angle studies of Pt, Ag, and SU-8 ink.
- Printing the Pt, $Ti_3C_2T_x$, Ag, and SU-8 ink as electrochemical biosensor.
- Surface treatment of printed $Ti_3C_2T_x$.
- Electrochemical performance of printed sensor.

Acknowledgements

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